

bq2512x Evaluation Module

The bq2512x evaluation module (EVM) is a high-performance, easy-to-use development kit for the design of a compact, flexible, high-efficiency, lower power management solution for single-cell, Li-ion and Li-polymer batteries used in wearables and low-power portable applications.

This user's guide details both the bq25120EVM and bq25121EVM features, test summary, and test results. Also included are the EVM schematic, bill of materials, and PCB board layouts.

PCB Configurations

| Device | PCB |
|---------|--------|
| bq25120 | PWR731 |
| bq25121 | PWR812 |

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1 Introduction

1.1 bq2512x IC Features

The bq2512x is a highly-integrated battery charge management IC that integrates the most common functions for wearable devices: linear charger, regulated output, load switch, manual reset with timer, and battery voltage monitor. The low quiescent current during operation and shutdown enables maximum battery life. The device supports charge currents from 5 mA to 300 mA. The input current limit, charge current, PWM output voltage, LDO output voltage, and other parameters are programmable through the I²C interface. The battery is charged using a standard Li-Ion charge profile with three phases: precharge, constant current, and constant voltage.

1.2 bq2512x EVM Features

The bq2512x EVM is a complete battery power management module for evaluating compact, highly-integrated, flexible, high efficiency, linear charging solution for single cell, Li-Ion and Li-Polymer battery-powered systems used in wearables and low-power portable applications. Key EVM features include:

- Configurable 300-mA buck regulator (1.8-V default)
- 700-nA typical I_Q with PWM enabled
- 0.5% accurate battery voltage regulation (configurable from 3.6 V to 4.65 V in 10-mV steps)
- Configurable termination current down to 500 μA
- 2.5 mm × 2.5 mm WCSP package and 6 external components for minimum solution
- Power path management for powering the system and charging the battery
- Power path management enables < 150 nA ship mode battery quiescent current for longest shelf life
- Push-button wake-up and reset with adjustable timers
- Battery charger operates from 3.4 V – 5.5 V V_{IN} (5.5-V OVP / 20-V tolerant)
- I²C control of key parameters

1.3 Schematic

Figure 1 illustrates the EVM schematic.

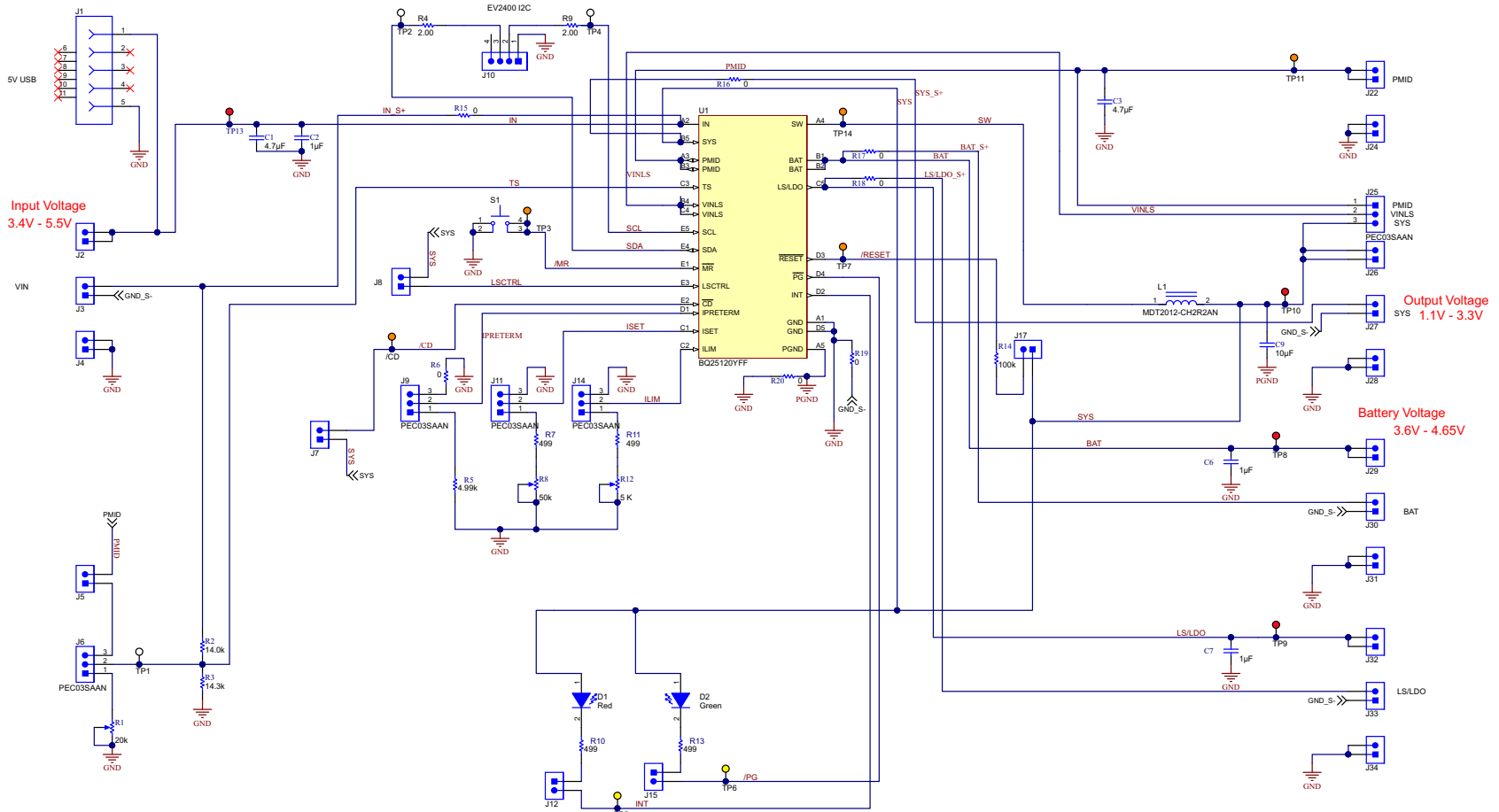


Figure 1. bq2512xEVM Schematic (bq25120 Represented)

1.4 I/O Description

Table 1 lists the descriptions of the IO connectors on the PCB.

Table 1. Description of the IO Connectors on PCB

| Header or Terminal Block | Description |
|----------------------------|--|
| J1 - USB power input | Micro USB connector for USB input power |
| J2 - IN (Force line) | Headers for extra connections to IN-Force |
| J3 - IN/GND (Sense line) | Headers for IN-Sense and GND |
| J4 - GND | Headers for extra connections to GND |
| J5 - TS to PMID | Headers for TS pin to be pulled up to PMID |
| J6 - TS | Headers for TS pin to be connected either to PMID or external resistor |
| J7 - CD | Headers for /CD pin to be pulled up to SYS pin |
| J8 - LS/CTRL | Headers for LS/CTRL pin to be pulled up to SYS pin |
| J9 - IPRETERM | Headers for IPRETERM pin to be connected to an external resistor or shorted to GND |
| J10 - EV2400 | The 4-wire connector for EV2400 communication interface |
| J11 - ISET | Headers for ISET pin to be connected to an external resistor or shorted to GND |
| J12 - INT | Headers for INT pin to be pulled up to SYS pin through a LED light |
| J14 - ILIM | Headers for ILIM pin to be connected to an external resistor or shorted to GND |
| J15 - /PG | Headers for /PG pin to be pulled up to SYS pin through a LED light |
| J17 - /RESET | Headers for /RESET pin to be pulled up to SYS pin through a 100-kΩ resistor |
| J22 - PMID | Headers for extra connections to PMID |
| J24 - GND | Headers for extra connections to GND |
| J25 - PMID/VINLS/SYS | Headers for PMID/VINLS/SYS connections |
| J26 - SYS | Headers for extra connections to SYS-Force |
| J27 - SYS/GND (Sense line) | Headers for SYS-Sense and GND |
| J28 - GND | Headers for extra connections to GND |
| J29 - BAT | Headers for extra connections to BAT-Force |
| J30 - BAT/GND (Sense line) | Headers for BAT-Sense and GND |
| J31 - GND | Headers for extra connections to GND |
| J32 - LS/LDO | Headers for extra connections to LS/LDO-Force |
| J33 - LS/LDO (Sense line) | Headers for LS/LDO-Sense and GND |
| J34 - GND | Headers for extra connections to GND |

1.5 Test Points

Table 2 provides descriptions of the test points.

Table 2. Test Points Description

| Test Points | Description |
|-------------|-------------|
| TP1 | TS pin |
| TP2 | SDA pin |
| TP3 | /MR pin |
| TP4 | SCL pin |
| TP5 | INT pin |
| TP6 | /PG pin |
| TP7 | /RESET pin |
| TP8 | BAT pin |
| TP9 | LS/LDO pin |
| TP10 | SYS pin |
| TP11 | PMID pin |
| TP13 | IN pin |
| TP14 | SW pin |
| TP /CD | /CD pin |

1.6 Default Settings

The bq2512xEVM module has provided the capability of changing key parameters using I²C and the EV2400 communication interface. However, I²C communication is not required for this device to operate. The module is programmed to the default settings as is described in Table 3, Table 4 shows the initial jumper positions on the PCB.

Table 3. Default Settings

| Parameter | Options | bq2512x |
|-------------------|----------------------------------|---------|
| BAT_UVLO | 2.2 V to 3.4 V (200-mV step) | 3.0 V |
| VSYS | 1.1 V to 3.3 V (100-mV step) | 1.8 V |
| LS/LDO | LS, 0.8 V to 3.3 V (100-mV step) | LS |
| VBREG | 3.6 V to 4.65 V (10-mV step) | 4.2 V |
| ICHG | 5 mA to 300 mA | 10 mA |
| IPRETERM | 500 μ A to 50 mA | 2 mA |
| Input ILIM | 50 mA to 400 mA (50-mA step) | 100 mA |
| VIN_DPM_ON | On or Off | On |
| VIN_DPM Threshold | 4.2 V to 4.9 V | 4.6 V |
| Auto Charge | On or Off | On |
| Safety Timer | 30 min, 3 hr, 9 hr, Disabled | 3 hr |

Table 4. Initial Jumper Position

| J6 | J9 | J11 | J12 | J14 | J15 | J25 |
|-------------|-------------|-----------|-----------|------------|-----------|--------------|
| TS = TS_Pot | ITERM = GND | ISET= GND | Installed | ILIM = GND | Installed | VINLS = PMID |

1.7 Recommended Operating Conditions

The recommended operating conditions are shown in Table 5.

Table 5. Recommended Operating Conditions⁽¹⁾⁽²⁾

| | | MIN | NOM | MAX | Unit |
|--------------------|---|-----|-----|--------|------|
| V_{IN} | IN voltage range | 3.4 | 5 | 20 | V |
| | IN operating voltage range, recommended | 3.4 | 5 | 5.5 | |
| V_{BAT} | VBAT operating voltage range | | | 5.5(1) | V |
| V_{VINLS} | VINLS voltage range for Load Switch | 0.8 | | 5.5(2) | V |
| V_{VINLS} | VINLS voltage range for LDO | 2.2 | | 5.5 | V |
| I_{IN} | Input Current, IN input | | | 400 | mA |
| I_{SW} | Output Current from SW, DC | | | 300 | mA |
| I_{PMID} | Output Current from PMID, DC | | | 300 | mA |
| $I_{LS/LDO}$ | Output Current from LS/LDO | | | 100 | mA |
| I_{BAT}, I_{SYS} | Charging and discharging using internal battery FET | | | 300 | mA |
| T_J | Operating junction temperature range | -40 | | 125 | °C |

(1) Any voltage greater than shown should be a transient event.

(2) These inputs will support 6.6 V for less than 10% of the lifetime at $V_{(BAT)}$ or V_{IN} , with a reduced current and/or performance.

2 Test Summary

This section describes the test configuration of the bq2512xEVM evaluation module for bench evaluation.

2.1 Recommended Test Equipment

2.1.1 Power Supplies

1. Power Supply #1 (PS#1): a power supply capable of supplying 5 V at 1 A is required.
2. Power Supply #2 (PS#2): a power supply capable of supplying 5 V at 1 A is required.

2.1.2 Load

Testing with an actual battery is the best way to verify operation in the system. If a battery is unavailable, then a source meter like a Keithley 2420, capable of both sourcing and sinking current, or a circuit similar to the one shown in Figure 2 can simulate a battery when connected to PS#2.

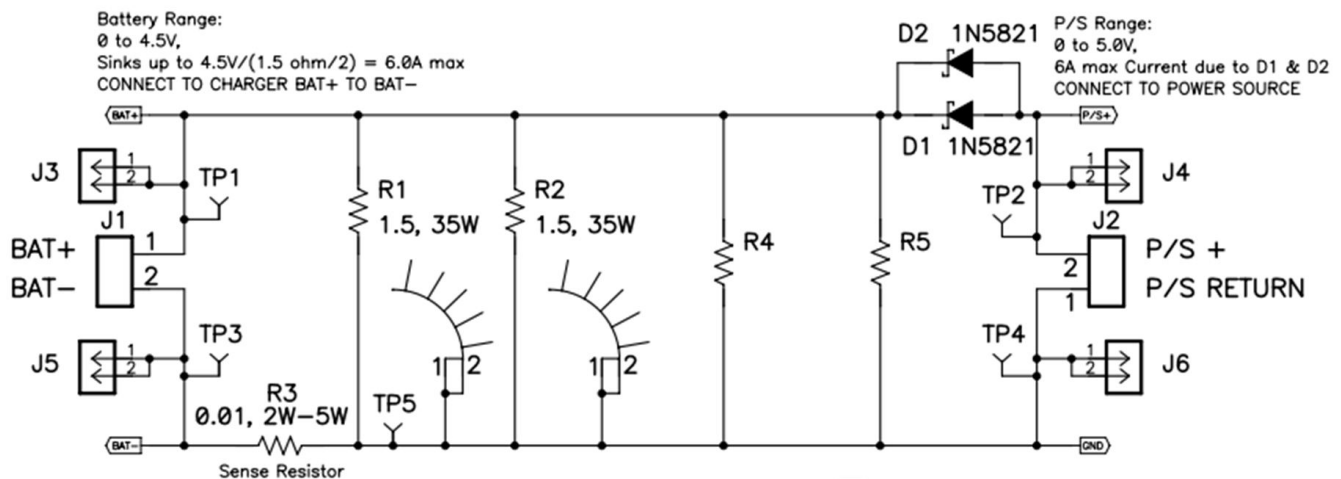


Figure 2. BAT Load (PR1010) Schematic

2.1.3 Meters

Three voltage meters and two current meters. The current meters must be able to measure at least 0.5-A current.

2.1.4 Tool/Software GUI (Optional)

The following optional items can be used for testing:

1. [EV2400](#) Communication Interface Board
2. [bqStudio](#) Software GUI

2.2 Recommended Test Equipment Setup

The following guidelines provide the recommended test equipment setup:

1. Set power supply #1 (PS#1) for 5 V \pm 100 mV DC, 1-A current limit and then turn off supply. Set power supply #2 (PS#2) for 3.5 V and then turn off supply.
2. Connect the positive output of PS#1 through a current meter (CM#2) to IN (J2) and negative output to GND (J34).
3. Connect a voltage meter (VM#1) across J2 and J34.
4. Connect the PR1010 BAT+ terminal of PR1010 in series with a current meter (CM#1) to BAT (J29). Connect PR1010 BAT – to GND (J34). Connect the P/S+ and P/S return side of PR1010 to PS#2, set the voltage to 3.5 V \pm 50 mV, then disable PS#2.
5. Connect a voltage meter (VM#2) across BAT (J29) and GND (J34).
6. Connect a DMM (VM#3) across SYS (SYS_S+ of J27) and GND (GND_S– of J27).
7. Configure jumpers as shown in [Table 4](#).

After the preceding steps are accomplished, the test setup for PWR731 is as shown in [Figure 3](#). The setup is similar for PWR812 with the bq25121.

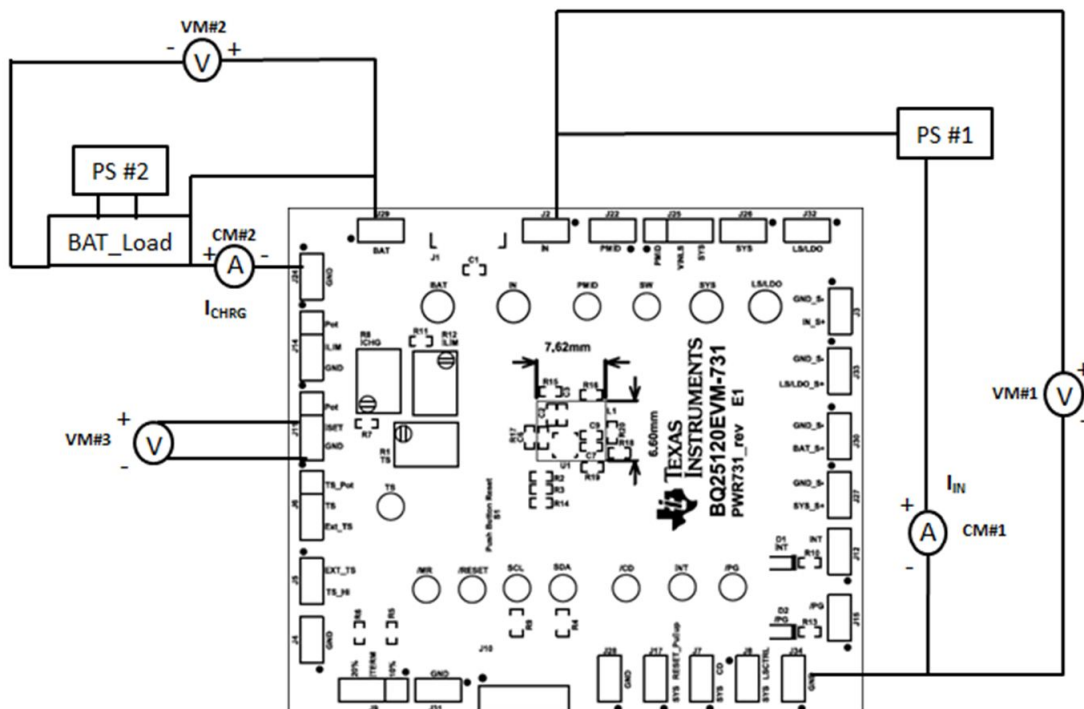


Figure 3. Test Setup (PWR731 for bq2512xEVM-731 Shown)

2.3 Software GUI (When I²C Communication is Used)

When using I²C communication, implement the following steps with the software GUI:

1. Install the [bqStudio](#) software GUI.
2. Connect the EV2400 interface board to the EVM (as shown in [Figure 4](#)) <http://www.ti.com/tool/EV2400>.
3. Open Software GUI and go to “Field View” page (as shown in [Figure 5](#)).
4. Change the parameters in the pull-down menu or check/uncheck the selection box.

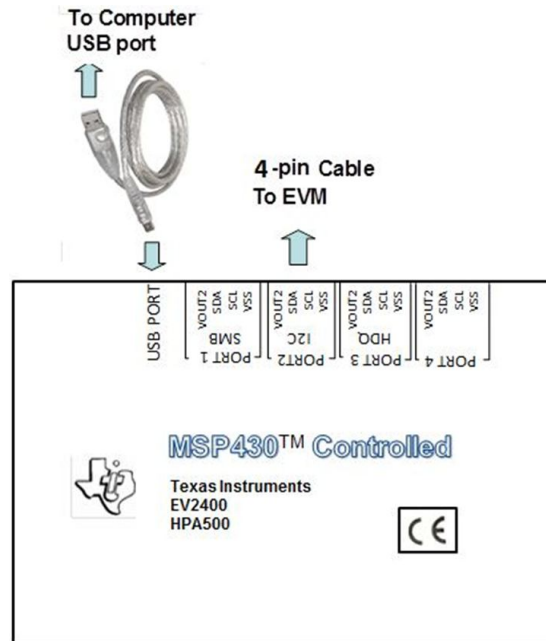


Figure 4. EV2400 Interface Box Connection

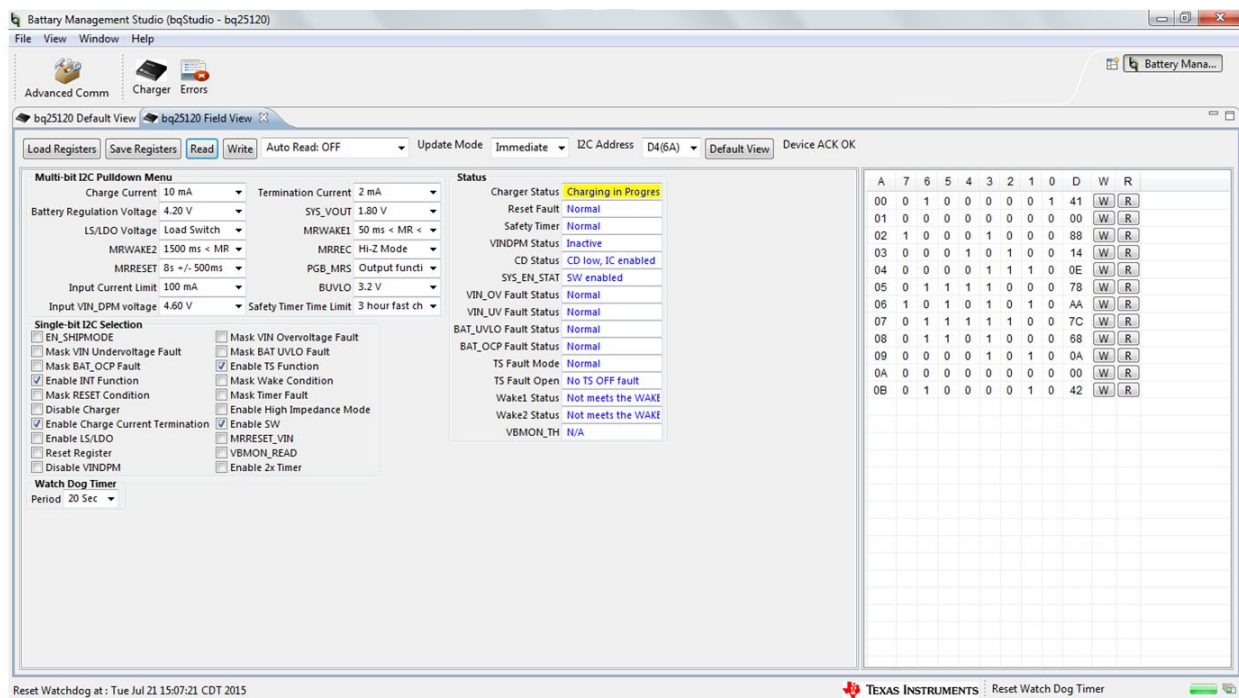


Figure 5. bq2512x Software GUI

3 Test Procedure

3.1 Set the Potentiometers

1. Set VM#3 DMM to measure resistance
2. Install J11 to POT
3. Install J14 to POT
4. Turn the potentiometer R8 until the measure on VM#3 → R[J11 (ISET), J11(GND)] = 2 kΩ.
5. Move the positive side of VM#3 DMM to J14 (ILIM).
6. Turn the potentiometer R12 until the measure on VM#3 → R[J14(ILIM), J14(GND)] = 499 Ω.
7. Move the positive side of VM#3 DMM to J6 (TS).
8. Turn the potentiometer R1 until the measure on VM#3 → R[J6 (TS), J14(GND)] = 5.5 kΩ – 6.5 kΩ.
9. Move the positive side of VM#3 DMM to J27 (SYS_S+).
10. Set VM#3 DMM to measure voltage.

3.2 Charge Disabled

1. Install the jumper on J7 – connect CD to SYS
2. Enable PS#1 and PS#2
3. Observe D2 is on, D1 is off
4. Measure on VM#3 → V[J27(SYS_S+) J14(GND)] = 1.8V ±50 mV
5. Measure on CM#2 → ICHRG ≤ 0–1 mA
6. Measure on CM#1 → IIN < 2 mA
7. Disable PS#1 and PS#2

3.3 Charge Current Regulation

1. Remove the jumper on J7 – disconnect CD to SYS
2. Enable PS#1 and PS#2
3. Observe D2 is on, D1 is on
4. Adjust PS#2 so that the voltage measured by VM#2, across BAT and GND, measures 3.5 V
5. Adjust the PS#1 so that VM#1 still reads 5.0 V ±100 mV
6. Measure on VM#3 → V[J27(SYS_S+) J14(GND)] = 1.8 V ±50 mV
7. Measure on CM#2 → ICHRG = 90–110 mA
8. Measure on CM#1 → IIN = 93–113 mA
9. Disable PS#1 and PS#2

3.4 Ship Mode (Optional if FC Control not Used)

1. Enable PS#1 and PS#2
2. Open the software GUI
3. Go to Field View of the GUI and then read all the registers. All the default register values should be shown in the register map (as shown in [Figure 3](#)).
4. Measure on CM#2 → ICHRG = 9–11 mA
5. Install the jumper on J7 – connect CD to SYS
6. Disable PS#1
7. Measure on CM#2 → ICHRG = 5–7 μA
8. Check the box in front of “EN_SHIPMODE” in the software GUI

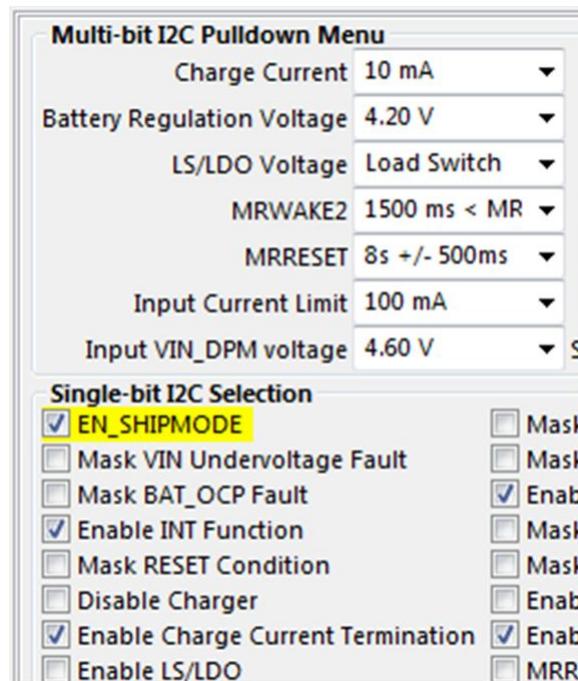


Figure 6. Select EN_SHIPMODE

9. Measure on CM#2 → ICHRG < 100 nA
10. Disable PS#2

4 Helpful Hints

The following steps provide useful information when using the EVM:

1. The leads and cables to the various power supplies have resistance. The current meters also have series resistance. Therefore, voltmeters must be used to measure the voltage as close to the IC pins as possible instead of relying on each supply's digital measurement.
2. When using a source meter as your battery simulator, it is highly recommended to configure the source meter for 4-wire sensing, eliminating the need for a separate voltmeter to measure the voltage at the OUT pin.
3. To observe the taper current as the battery voltage approaches the set regulation voltage, allow the battery to charge, or if using BAT_Load (PR1010), slowly increase the PS#2 voltage powering BAT_Load (PR1010). Use VM#2 across OUT and GND to measure the battery voltage seen by the IC.
4. To find out more details about battery I_Q and how to measure it on power supplies, please refer to the application note: *IQ: What it is, what it isn't, and how to use it* ([SLYT412](#))

5 Bill of Materials and Board Layout

This section provides the bq2512x EVM bill of materials (BOM) and the printed-circuit board (PCB) layout illustrations.

5.1 Bill of Materials

Table 6 lists the EVM BOM.

Table 6. bq2512xEVM Bill of Materials

| Item # | Designator | Qty | Value | Part Number | Manufacturer | Description | Package Reference |
|--------|--|-----|-------|---------------------|-----------------------------|--|-----------------------------|
| 1 | !PCB | 1 | | PWR812 | Any | Printed Circuit Board | |
| 2 | C1, C3 | 2 | 4.7uF | GRM188R61E475KE11D | Murata | CAP, CERM, 4.7 μ F, 25 V, +/- 10%, X5R, 0603 | 0603 |
| 3 | C2 | 1 | 1uF | C1005X5R1E105K050BC | TDK | CAP, CERM, 1 μ F, 25 V, +/- 10%, X5R, 0402 | 0402 |
| 4 | C6, C7 | 2 | 1uF | GRM155R61A105KE15D | Murata | CAP, CERM, 1 μ F, 10 V, +/- 10%, X5R, 0402 | 0402 |
| 5 | C9 | 1 | 10uF | CL05A106MP5NUNC | Samsung Electro-Mechanics | CAP, CERM, 10 μ F, 10 V, +/- 20%, X5R, 0402 | 0402 |
| 6 | D1 | 1 | Red | LTST-C190CKT | Lite-On | LED, Red, SMD | Red LED, 1.6x0.8x0.8mm |
| 7 | D2 | 1 | Green | LTST-C190GKT | Lite-On | LED, Green, SMD | 1.6x0.8x0.8mm |
| 8 | H12, H13, H14, H15 | 4 | | SJ61A1 | 3M | Bumpon, Cylindrical, 0.312 X 0.200, Black | Black Bumpon |
| 9 | J1 | 1 | | 105017-0001 | Molex | Receptacle, Micro-USB-B, Right Angle, SMD | Micro USB receptacle |
| 10 | J2, J3, J4, J5, J7, J8, J12, J15, J17, J22, J24, J26, J27, J28, J29, J30, J31, J32, J33, J34 | 20 | | PEC02SAAN | Sullins Connector Solutions | Header, 100mil, 2x1, Tin plated, TH | Header, 2 PIN, 100mil, Tin |
| 11 | J6, J9, J11, J14, J25 | 5 | | PEC03SAAN | Sullins Connector Solutions | Header, 100mil, 3x1, Tin, TH | Header, 3 PIN, 100mil, Tin |
| 12 | J10 | 1 | | 22-05-3041 | Molex | Header (friction lock), 100mil, 4x1, R/A, TH | 4x1 R/A Header |
| 13 | L1 | 1 | 2.2uH | LQM21PN2R2MGH | Murata | Inductor, Multilayer, Ferrite, 2.2 μ H, 0.7 A, 0.125 ohm, SMD | 2.0x1.0x1.2mm |
| 14 | LBL1 | 1 | | THT-14-423-10 | Brady | Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll | PCB Label 0.650"H x 0.200"W |
| 15 | R1 | 1 | 20k | 3266W-1-203LF | Bourns | Trimmer, 20k ohm, 0.25W, TH | 4.5x8x6.7mm |
| 16 | R2 | 1 | 14.0k | CRCW040214K0FKED | Vishay-Dale | RES, 14.0k ohm, 1%, 0.063W, 0402 | 0402 |
| 17 | R3 | 1 | 14.3k | CRCW040214K3FKED | Vishay-Dale | RES, 14.3k ohm, 1%, 0.063W, 0402 | 0402 |
| 18 | R4, R9 | 2 | 2.00 | CRCW06032R00FKEA | Vishay-Dale | RES, 2.00 ohm, 1%, 0.1W, 0603 | 0603 |
| 19 | R5 | 1 | 4.99k | CRCW04024K99FKED | Vishay-Dale | RES, 4.99 k, 1%, 0.063 W, 0402 | 0402 |
| 20 | R6, R15, R16, R17, R18, R19, R20 | 7 | 0 | CRCW04020000Z0ED | Vishay-Dale | RES, 0, 5%, 0.063 W, 0402 | 0402 |

Table 6. bq2512xEVM Bill of Materials (continued)

| Item # | Designator | Qty | Value | Part Number | Manufacturer | Description | Package Reference |
|--------|--|-----|--------|------------------|-------------------|---|----------------------------|
| 21 | R7, R10, R11, R13 | 4 | 499 | CRCW0402499RFKED | Vishay-Dale | RES, 499 ohm, 1%, 0.063W, 0402 | 0402 |
| 22 | R8 | 1 | 50k | 3266W-1-503LF | Bourns | Trimmer, 50k ohm, 0.25W, TH | 4.5x8x6.7mm |
| 23 | R12 | 1 | 5 K | 3266W-1-502LF | Bourns | Trimmer, 5k ohm, 0.25W, TH | 4.5x8x6.7mm |
| 24 | R14 | 1 | 100k | CRCW0402100KFKED | Vishay-Dale | RES, 100k ohm, 1%, 0.063W, 0402 | 0402 |
| 25 | S1 | 1 | | KST221JLFS | C&K Components | Switch, Tactile, SPST-NO, SMT | Switch, 6.2X5X6.2 mm |
| 26 | SH-JP1, SH- JP2, SH-JP3, SH-JP4, SH- JP5, SH-JP6, SH-JP7 | 7 | 1x2 | 969102-0000-DA | 3M | Shunt, 100mil, Gold plated, Black | Shunt |
| 27 | TP1, TP2, TP4 | 3 | White | 5002 | Keystone | Test Point, Miniature, White, TH | White Miniature Testpoint |
| 28 | TP3, TP7, TP11, TP14, TP15 | 5 | Orange | 5003 | Keystone | Test Point, Miniature, Orange, TH | Orange Miniature Testpoint |
| 29 | TP5, TP6 | 2 | Yellow | 5004 | Keystone | Test Point, Miniature, Yellow, TH | Yellow Miniature Testpoint |
| 30 | TP8, TP9, TP10, TP13 | 4 | Red | 5005 | Keystone | Test Point, Compact, Red, TH | Red Compact Testpoint |
| 31 | U1 | 1 | | BQ25121YFPR | Texas Instruments | 700-nA Low IQ Highly Integrated Battery Charge Management Solution for Wearables and IoT, YFP0025BABD | YFP0025BABD |
| 32 | FID1, FID2, FID3, FID4, FID5, FID6 | 0 | | N/A | N/A | Fiducial mark. There is nothing to buy or mount. | Fiducial |

5.2 Board Layouts

5.2.1 PWR731 Layouts

Figure 7 through Figure 16 illustrate the PWR731 EVM PCB board layouts.

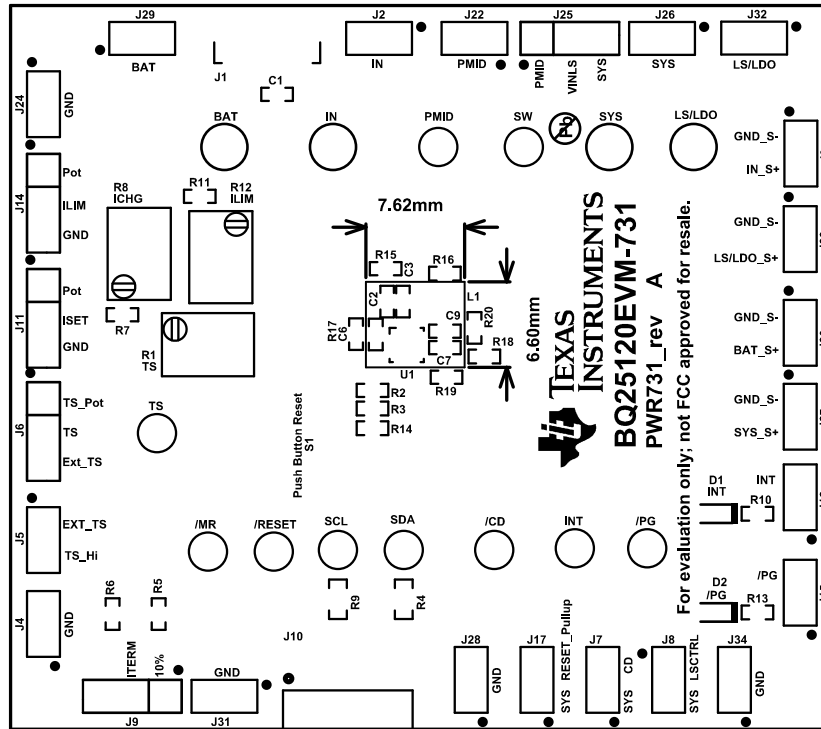


Figure 7. Top Overlay

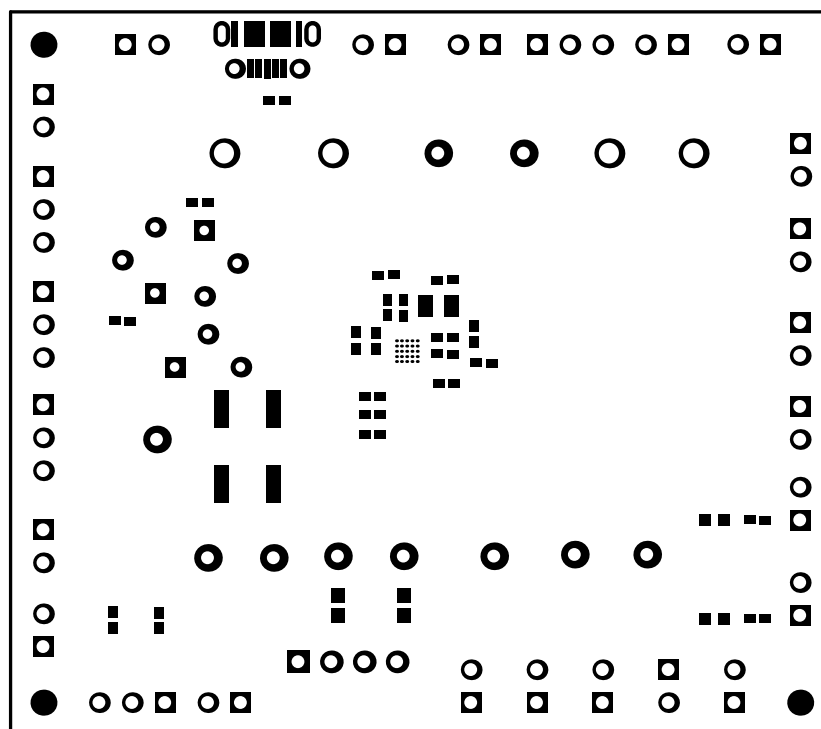


Figure 8. Top Solder Mask

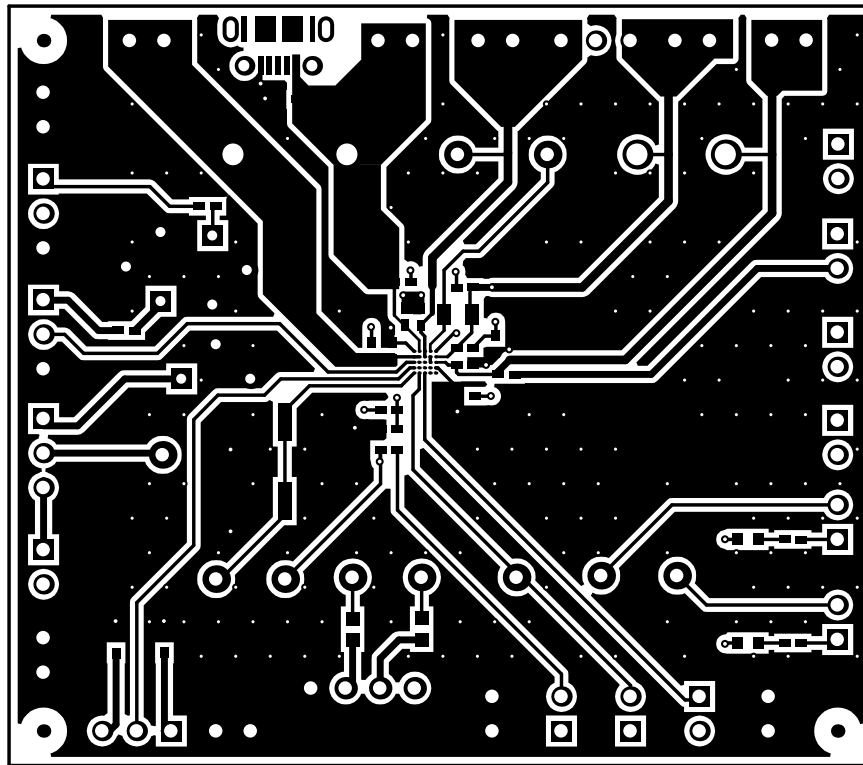


Figure 9. Top Layer

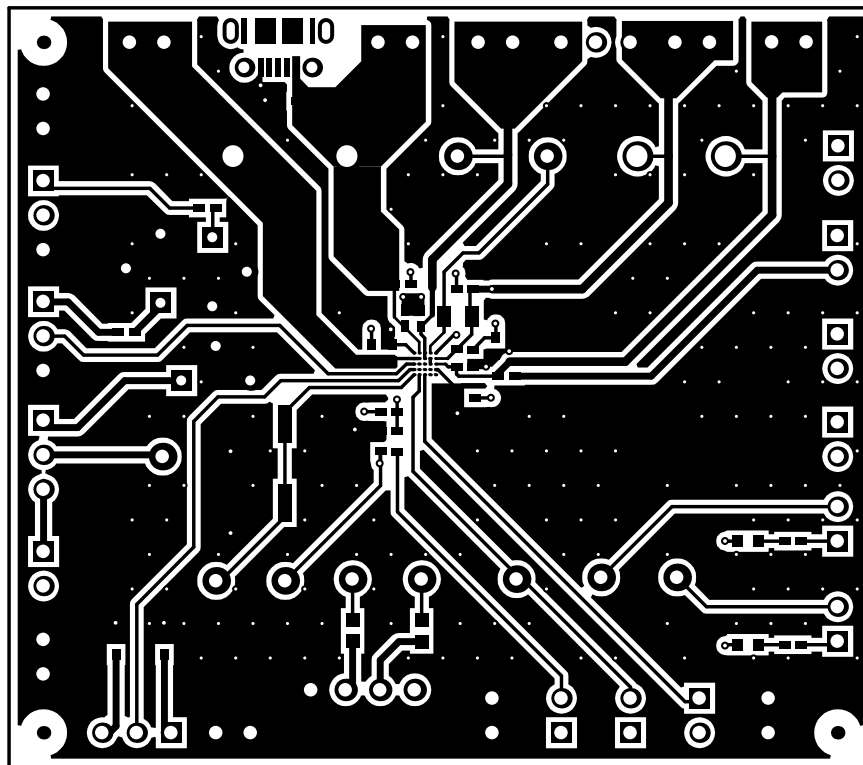


Figure 10. Signal Layer 1

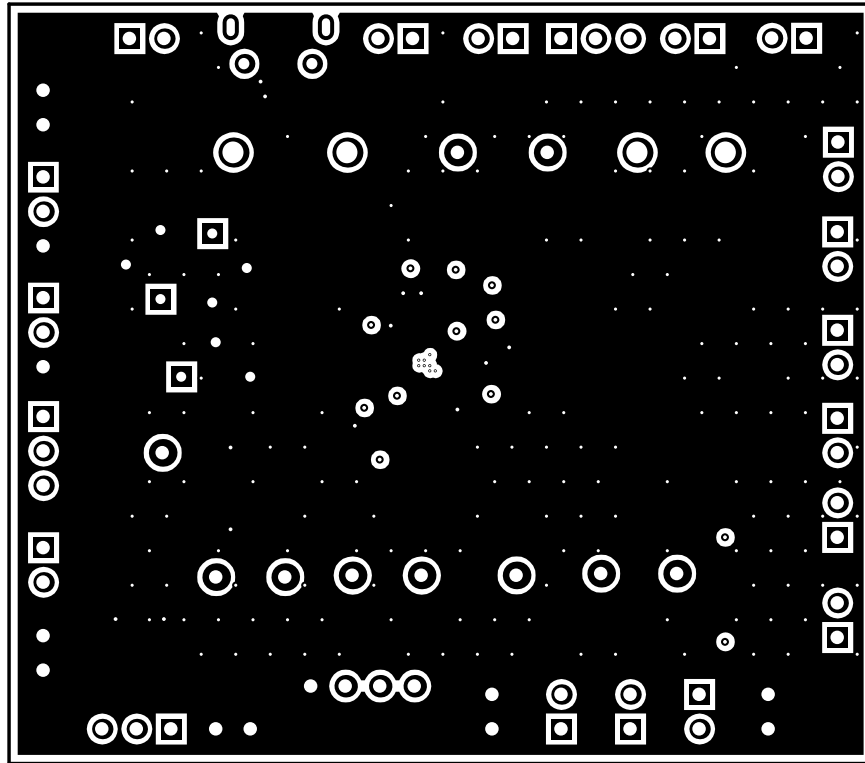


Figure 11. Signal Layer 2

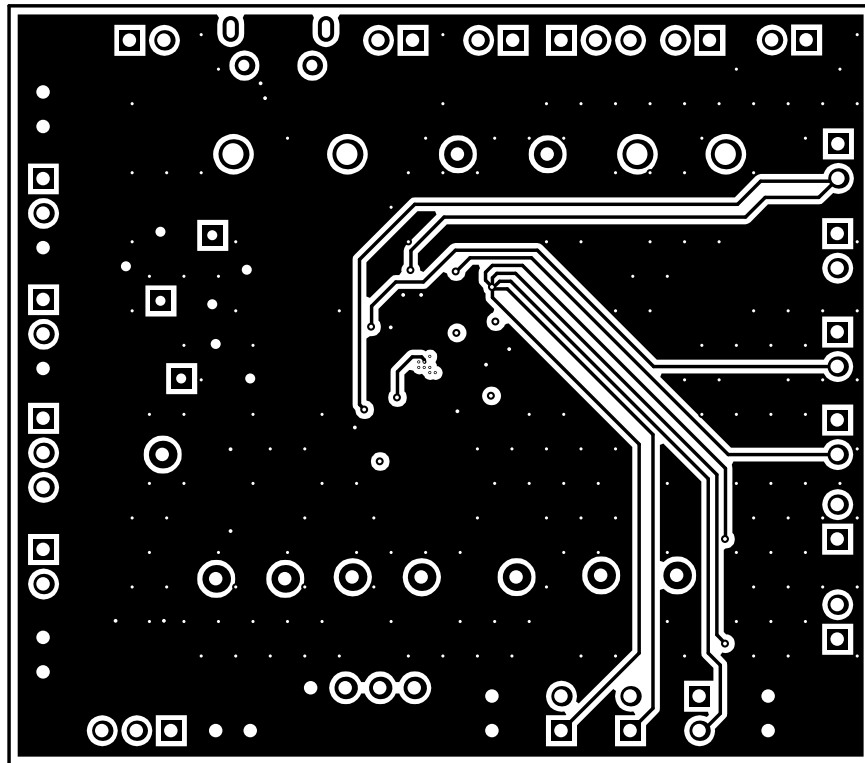


Figure 12. Bottom Layer

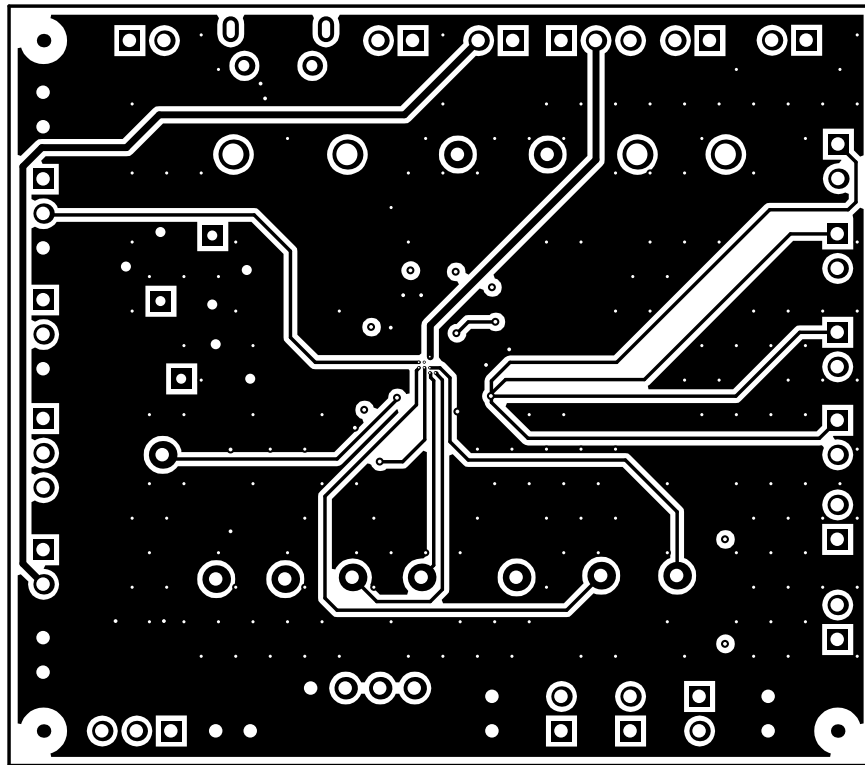


Figure 13. Bottom Solder Mask

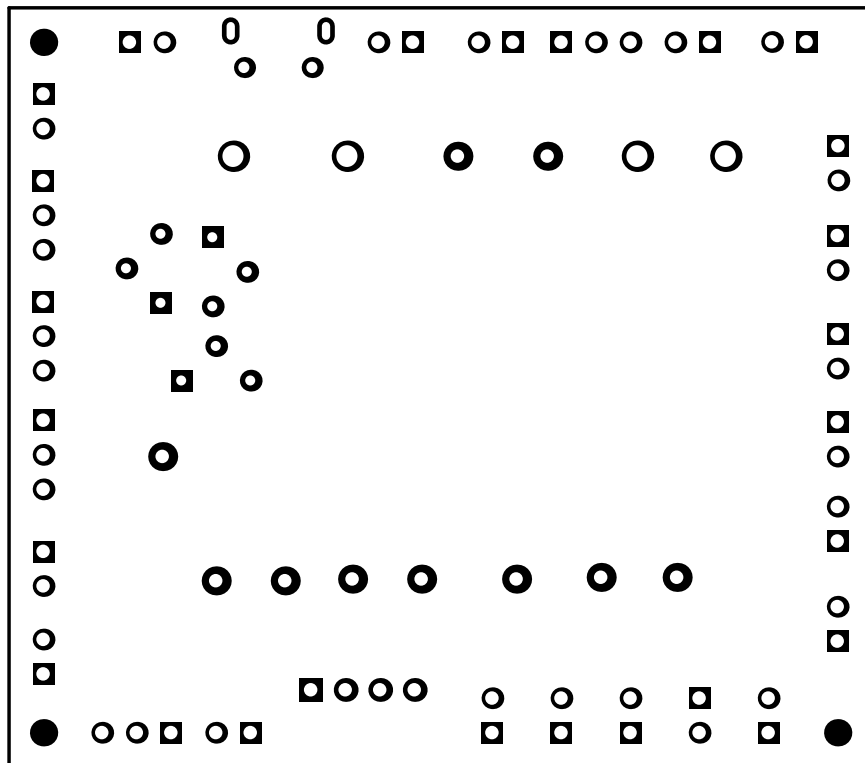


Figure 14. Bottom Overlay

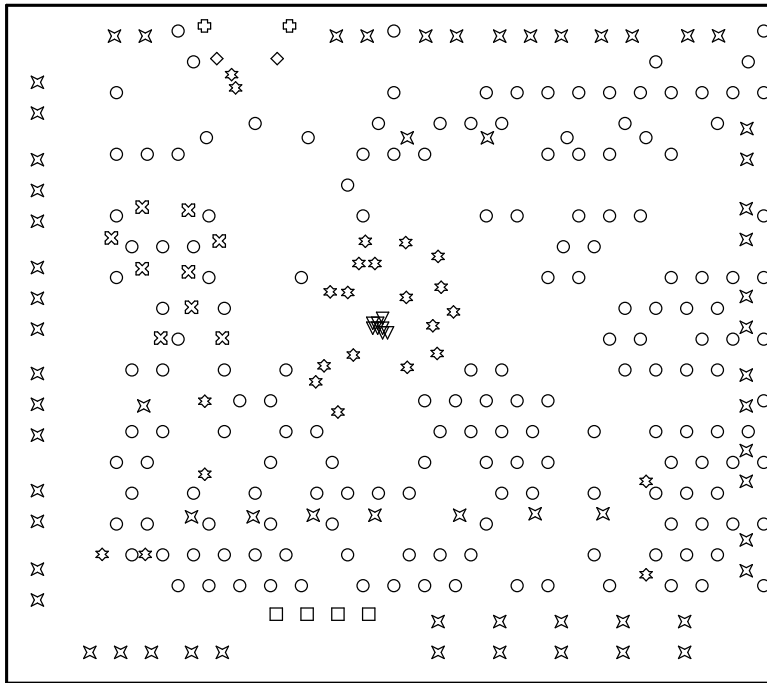


Figure 15. Drill Drawing

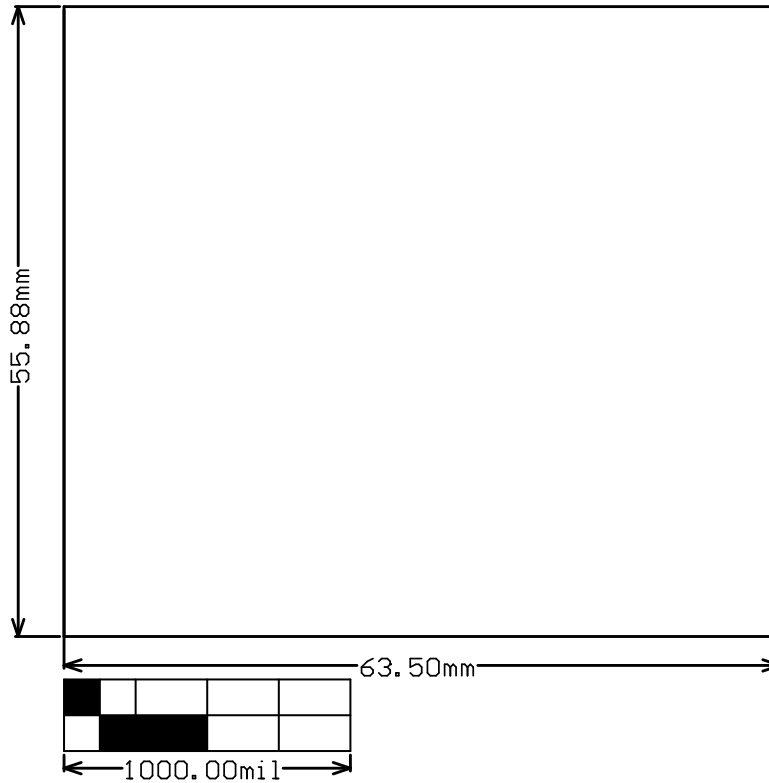
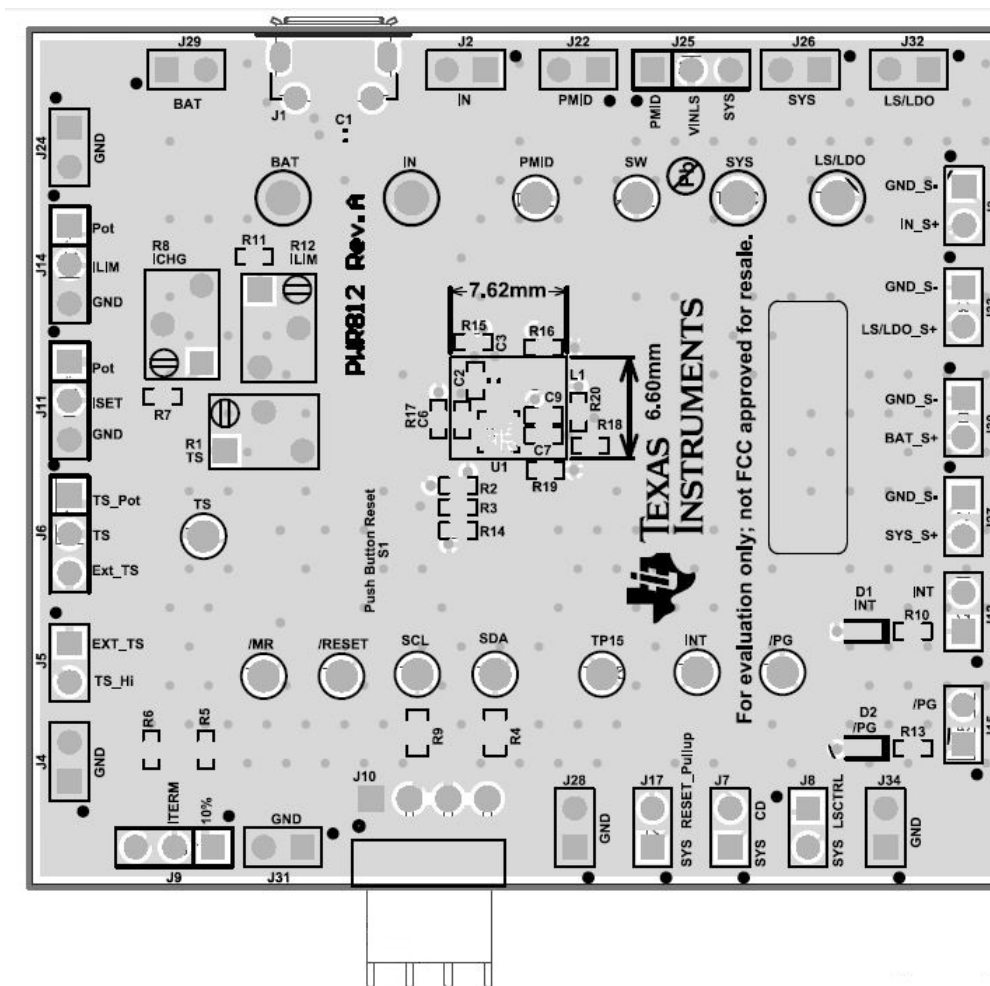


Figure 16. Board Dimensions

5.2.2 PWR812 Layout

Figure 17 illustrates the PWR812 PCB composite layout.



Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Original (August 2015) to A Revision

Page

- Changed user's guide globally to accommodate both the bq25120 and bq25121 EVMs. 1
- Replaced existing BOM with PWR812A BOM. 11

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This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.
 - 3.1.2 *For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:*

CAUTION

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

FCC Interference Statement for Class A EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

FCC Interference Statement for Class B EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

3.2 Canada

3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210

Concerning EVMs Including Radio Transmitters:

This device complies with Industry Canada license-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concernant les EVMs avec appareils radio:

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Concerning EVMs Including Detachable Antennas:

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

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http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_01.page

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1. Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.

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